



Programmable System-on-Chip (PSoC)

General Description

PSoC[®] 4 is a scalable and reconfigurable platform architecture for a family of programmable embedded system controllers with an Arm[®] Cortex™-M0+ CPU. It combines programmable and reconfigurable analog and digital blocks with flexible automatic routing. The PSoC 4000S product family is a member of the PSoC 4 platform architecture. It is a combination of a microcontroller with standard communication and timing peripherals, a capacitive touch-sensing system (CapSense) with best-in-class performance, programmable general-purpose continuous-time and switched-capacitor analog blocks, and programmable connectivity. PSoC 4000S products are upward compatible with members of the PSoC 4 platform for new applications and design needs.

Features

32-bit MCU Subsystem

- 48-MHz Arm Cortex-M0+ CPU with single-cycle multiply
- Up to 32 KB of flash with Read Accelerator
- Up to 4 KB of SRAM

Programmable Analog

- Single-slope 10-bit ADC function provided by Capacitance sensing block
- Two current DACs (IDACs) for general-purpose or capacitive sensing applications on any pin
- Two low-power comparators that operate in Deep Sleep low-power mode

Programmable Digital

Programmable logic blocks allowing Boolean operations to be performed on port inputs and outputs

Low-Power 1.71-V to 5.5-V Operation

■ Deep Sleep mode with operational analog and 2.5 µA digital system current

Capacitive Sensing

- Cypress CapSense Sigma-Delta (CSD) provides best-in-class signal-to-noise ratio (SNR) (>5:1) and water tolerance
- Cypress-supplied software component makes capacitive sensing design easy
- Automatic hardware tuning (SmartSense[™])

LCD Drive Capability

LCD segment drive capability on GPIOs

Serial Communication

Two independent run-time reconfigurable Serial Communication Blocks (SCBs) with re-configurable I²C, SPI, or UART functionality

Timing and Pulse-Width Modulation

- Five 16-bit timer/counter/pulse-width modulator (TCPWM) blocks
- Center-aligned, Edge, and Pseudo-random modes
- Comparator-based triggering of Kill signals for motor drive and other high-reliability digital logic applications

Up to 36 Programmable GPIO Pins

- 48-pin TQFP, 40-pin QFN, 32-pin QFN, 24-pin QFN, 32-pin TQFP, and 25-ball WLCSP packages
- Any GPIO pin can be CapSense, analog, or digital
- Drive modes, strengths, and slew rates are programmable

Clock Sources

- 32-kHz Watch Crystal Oscillator (WCO)
- ±2% Internal Main Oscillator (IMO)
- 32-kHz Internal Low-power Oscillator (ILO)

ModusToolbox™ Software

- Comprehensive collection of multi-platform tools and software libraries
- Includes board support packages (BSPs), peripheral driver library (PDL), and middleware such as CapSense

PSoC Creator Design Environment

- Integrated development environment (IDE) provides schematic design entry and build, with analog and digital automatic routing
- Application programming interface (API) Components for all fixed-function and programmable peripherals

Industry-Standard Tool Compatibility

After schematic entry, development can be done with Arm-based industry-standard development tools

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Development Ecosystem

PSoC 4 MCU Resources

Cypress provides a wealth of data at www.cypress.com to help you select the right PSoC device and quickly and effectively integrate it into your design. The following is an abbreviated, hyperlinked list of resources for PSoC 4 MCU:

- Overview: PSoC Portfolio, PSoC Roadmap
- Product Selectors: PSoC 4 MCU
- Application Notes cover a broad range of topics, from basic to advanced level, and include the following:
 - □ AN79953: Getting Started With PSoC 4. This application note has a convenient flow chart to help decide which IDE to use: ModusToolbox™ Software or PSoC Creator.
 - □ AN91184: PSoC 4 BLE Designing BLE Applications
 - □ AN88619: PSoC 4 Hardware Design Considerations
 - □ AN73854: Introduction To Bootloaders
 - □ AN89610: Arm Cortex Code Optimization
 - □ AN86233: PSoC 4 MCU Power Reduction Techniques
 - □ AN57821: Mixed Signal Circuit Board Layout
 - □ AN85951: PSoC 4, PSoC 6 CapSense Design Guide
- Code Examples demonstrate product features and usage, and are also available on Cypress GitHub repositories.
- Technical Reference Manuals (TRMs) provide detailed descriptions of PSoC 4 MCU architecture and registers.
- PSoC 4 MCU Programming Specification provides the information necessary to program PSoC 4 MCU nonvolatile memory.

■ Development Tools

- □ ModusToolbox™ Software enables cross platform code development with a robust suite of tools and software libraries.
- □ PSoC Creator is a free Windows-based IDE. It enables concurrent hardware and firmware design of PSoC 3, PSoC 4, PSoC 5LP, and PSoC 6 MCU based systems. Applications are created using schematic capture and over 150 pre-verified, production-ready peripheral Components.
- □ CY8CKIT-145-40XX PSoC 4000S CapSense Prototyping Kit, is a low-cost and easy-to-use evaluation platform. This kit provides easy access to all the device I/Os in a breadboard-compatible format.
- □ MiniProg4 and MiniProg3 all-in-one development programmers and debuggers.
- □ PSoC 4 MCU CAD libraries provide footprint and schematic support for common tools. IBIS models are also available.
- Training Videos are available on a wide range of topics including the PSoC 4 MCU 101 series.
- Cypress Developer Community enables connection with fellow PSoC developers around the world, 24 hours a day, 7 days a week, and hosts a dedicated PSoC 4 MCU Community.

Document Number: 002-00123 Rev. *N Page 2 of 42



ModusToolbox™ Software

ModusToolbox Software is Cypress' comprehensive collection of multi-platform tools and software libraries that enable an immersive development experience for creating converged MCU and wireless systems. It is:

- Comprehensive it has the resources you need
- Flexible you can use the resources in your own workflow
- Atomic you can get just the resources you want

Cypress provides a large collection of code repositories on GitHub, including:

- Board Support Packages (BSPs) aligned with Cypress kits
- Low-level resources, including a peripheral driver library (PDL)
- Middleware enabling industry-leading features such as CapSense
- An extensive set of thoroughly tested code example applications

ModusToolbox Software is IDE-neutral and easily adaptable to your workflow and preferred development environment. It includes a project creator, peripheral and library configurators, a library manager, as well as the optional Eclipse IDE for ModusToolbox, as Figure 1 shows. For information on using Cypress tools, refer to the documentation delivered with ModusToolbox software, and AN79953: Getting Started with PSoC 4.

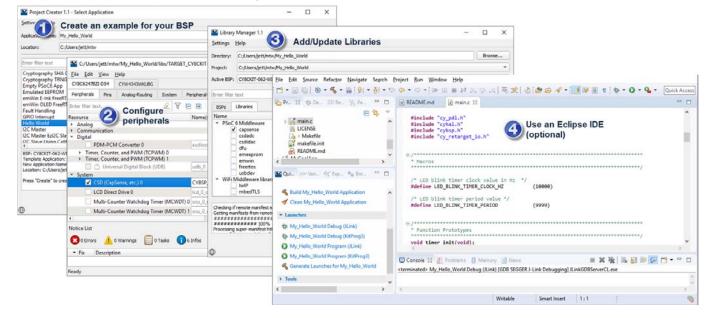


Figure 1. ModusToolbox Software Tools



PSoC Creator

PSoC Creator is a free Windows-based IDE. It enables you to design hardware and firmware systems concurrently, based on PSoC 4 MCU. As Figure 2 shows, with PSoC Creator you can:

- 1. Drag and drop Component icons to build your hardware system design in the main design workspace
- 2. Co-design your application firmware with the PSoC hardware, using the PSoC Creator IDE C compiler
- 3. Configure components using the configuration tools
- 4. Explore the library of 100+ components
- 5. Review component datasheets
- 6. Prototype your solution with the PSoC 4 Pioneer kits. If a design change is needed, PSoC Creator and Components enable you to make changes on-the-fly without the need for hardware revisions.

File Edit View Project Build Debug Tools Start Page TopDesigns 💌 🏥 🛎 🤌 👸 👺 燕 🗼 Microsoft Sans Serif ·10 · B / U E B 国 A·2·3· , 113% · Q Q , 少与私业公司五公园的。 Start Page TopDesign.cysch 外区回居尼 ₽ Q Closed-Loop Fan C Temperature Sensors and Fans Analog Temperature Sensing Host Processor CLFC (I2C-Based Data Motor support PWM o Support for up to 16 PWM-controlled, 4-wire brushless DC fans to PSoC 3/PSoC 5LP devices and up to 6 fans for PSoC 4 PWM frequency 6-pole motors PWM resolution: 8 bit • Supports 25 kHz, 50 kHz or user-specifie ints (A, B) from duty cycle to RPM cu Duty cycle A (%) RPM A Duty cycle B (%) Supports 4-pole and 6-pole motors Inst N Supports fan stall / rotor lock detec 100 1000 100 1000 eoc 100 1000 fan1 fan2

OK

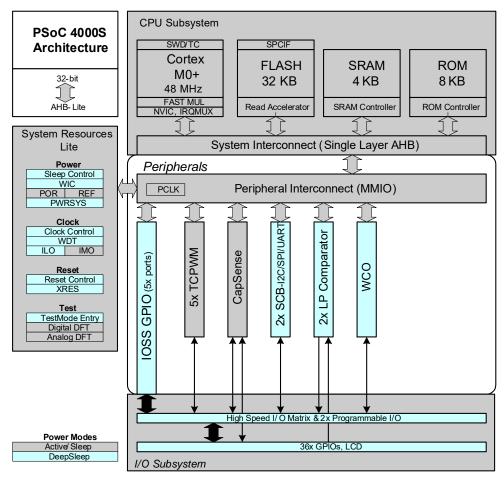
Figure 2. Multiple-Sensor Example Project in PSoC Creator

tach3

fan3



Logic Block Diagram



PSoC 4000S devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The Arm Serial-Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE provides fully integrated programming and debug support for the PSoC 4100S devices. The SWD interface is fully compatible with industry-standard third-party

tools. The PSoC 4000S provides a level of security not possible with multi-chip application solutions or with microcontrollers.

It has the following advantages:

- Allows disabling of debug features
- Robust flash protection
- Allows customer-proprietary functionality to be implemented in on-chip programmable blocks

The debug circuits are enabled by default and can be disabled in firmware. If they are not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging. Thus firmware control of debugging cannot be over-ridden without erasing the firmware thus providing security.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. All programming, debug, and test interfaces are

disabled when maximum device security is enabled. Therefore, PSoC 4000S, with device security enabled, may not be returned for failure analysis. This is a trade-off the PSoC 4000S allows the customer to make.



Functional Description

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Document Number: 002-00123 Rev. *N Page 6 of 42



Contents

Functional Definition	8
CPU and Memory Subsystem	
System Resources	
Analog Blocks	
Programmable Digital Blocks	
Fixed Function Digital	
GPIO	
Special Function Peripherals	10
Pinouts	1′
Alternate Pin Functions	12
Power	14
Mode 1: 1.8 V to 5.5 V External Supply	14
Mode 2: 1.8 V ±5% External Supply	
Electrical Specifications	1
Absolute Maximum Ratings	
Device Level Specifications	
Analog Peripherals	

Digital Peripherals	Z3
Memory	26
System Resources	
Ordering Information	
Packaging	
Package Diagrams	
Acronyms	
Document Conventions	
Units of Measure	38
Document History Page	39
Sales, Solutions, and Legal Information	
Worldwide Sales and Design Support	
Products	
PSoC® Solutions	42
Cypress Developer Community	42
Technical Support	



Functional Definition

CPU and Memory Subsystem

CPU

The Cortex-M0+ CPU in the PSoC 4000S is part of the 32-bit MCU subsystem, which is optimized for low-power operation with extensive clock gating. Most instructions are 16 bits in length and the CPU executes a subset of the Thumb-2 instruction set. It includes a nested vectored interrupt controller (NVIC) block with eight interrupt inputs and also includes a Wakeup Interrupt Controller (WIC). The WIC can wake the processor from Deep Sleep mode, allowing power to be switched off to the main processor when the chip is in Deep Sleep mode.

The CPU also includes a debug interface, the serial wire debug (SWD) interface, which is a two-wire form of JTAG. The debug configuration used for PSoC 4000S has four breakpoint (address) comparators and two watchpoint (data) comparators.

Flash

The PSoC 4000S device has a flash module with a flash accelerator, tightly coupled to the CPU to improve average access times from the flash block. The low-power flash block is designed to deliver two wait-state (WS) access time at 48 MHz. The flash accelerator delivers 85% of single-cycle SRAM access performance on average.

SRAM

Four KB of SRAM are provided with zero wait-state access at 48 MHz.

SROM

A supervisory ROM that contains boot and configuration routines is provided.

System Resources

Power System

The power system is described in detail in the section Power on page 14. It provides assurance that voltage levels are as required for each respective mode and either delays mode entry (for example, on power-on reset (POR)) until voltage levels are as required for proper functionality, or generates resets (for example, on brown-out detection). The PSoC 4000S operates with a single external supply over the range of either 1.8 V $\pm 5\%$ (externally regulated) or 1.8 to 5.5 V (internally regulated) and has three different power modes, transitions between which are managed by the power system. The PSoC 4000S provides Active, Sleep, and Deep Sleep low-power modes.

All subsystems are operational in Active mode. The CPU subsystem (CPU, flash, and SRAM) is clock-gated off in Sleep mode, while all peripherals and interrupts are active with instantaneous wake-up on a wake-up event. In Deep Sleep mode, the high-speed clock and associated circuitry is switched off; wake-up from this mode takes 35 µs.

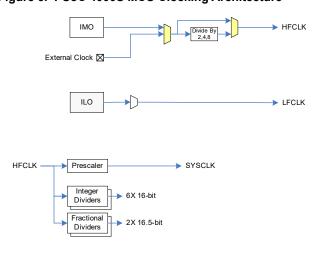
Clock System

The PSoC 4000S clock system is responsible for providing clocks to all subsystems that require clocks and for switching between different clock sources without glitching. In addition, the clock system ensures that there are no metastable conditions.

The clock system for the PSoC 4000S consists of the internal main oscillator (IMO), internal low-frequency oscillator (ILO), a 32 kHz Watch Crystal Oscillator (WCO) and provision for an external clock. Clock dividers are provided to generate clocks for peripherals on a fine-grained basis. Fractional dividers are also provided to enable clocking of higher data rates for UARTs.

The HFCLK signal can be divided down to generate synchronous clocks for the analog and digital peripherals. There are eight clock dividers for the PSoC 4000S, two of those are fractional dividers. The 16-bit capability allows flexible generation of fine-grained frequency values, and is fully supported in PSoC Creator.

Figure 3. PSoC 4000S MCU Clocking Architecture



IMO Clock Source

The IMO is the primary source of internal clocking in the PSoC 4000S. It is trimmed during testing to achieve the specified accuracy. The IMO default frequency is 24 MHz and it can be adjusted from 24 to 48 MHz in steps of 4 MHz. The IMO tolerance with Cypress-provided calibration settings is ±2%.

ILO Clock Source

The ILO is a very low power, nominally 40-kHz oscillator, which is primarily used to generate clocks for the watchdog timer (WDT) and peripheral operation in Deep Sleep mode. ILO-driven counters can be calibrated to the IMO to improve accuracy. Cypress provides a software component, which does the calibration.

Watch Crystal Oscillator (WCO)

The PSoC 4000S clock subsystem also implements a low-frequency (32-kHz watch crystal) oscillator that can be used for precision timing applications. The WCO block allows locking the IMO to the 32-kHz oscillator. The WCO on PSoC 4000S series devices does not connect to the LFCLK or WDT. Due to this, RTC functionality is not supported.



Watchdog Timer

A watchdog timer is implemented in the clock block running from the ILO; this allows watchdog operation during Deep Sleep and generates a watchdog reset if not serviced before the set timeout occurs. The watchdog reset is recorded in a Reset Cause register, which is firmware readable.

Reset

The PSoC 4000S can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset by asserting it active low. The XRES pin has an internal pull-up resistor that is always enabled.

Voltage Reference

The PSoC 4000S reference system generates all internally required references. A 1.2-V voltage reference is provided for the comparator. The IDACs are based on a ±5% reference.

Analog Blocks

Low-power Comparators (LPC)

The PSoC 4000S has a pair of low-power comparators, which can also operate in Deep Sleep modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode where the system wake-up circuit is activated by a comparator switch event. The LPC outputs can be routed to pins.

Current DACs

The PSoC 4000S has two IDACs, which can drive any of the pins on the chip. These IDACs have programmable current ranges.

Analog Multiplexed Buses

The PSoC 4000S has two concentric independent buses that go around the periphery of the chip. These buses (called amux buses) are connected to firmware-programmable analog switches that allow the chip's internal resources (IDACs, comparator) to connect to any pin on the I/O Ports.

Programmable Digital Blocks

The programmable I/O (Smart I/O) block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

Fixed Function Digital

Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. There are five TCPWM blocks in the PSoC 4000S.

Serial Communication Block (SCB)

The PSoC 4000S has two serial communication blocks, which can be programmed to have SPI, I2C, or UART functionality.

I²C Mode: The hardware I²C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 1 Mbps (Fast Mode Plus) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also supports EZI2C that creates a mailbox address range in the memory of the PSoC 4000S and effectively reduces I²C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I²C peripheral is compatible with the I²C Standard-mode and Fast-mode devices as defined in the NXP I²C-bus specification and user manual (UM10204). The I²C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4000S is not completely compliant with the I²C spec in the following respect:

■ GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I²C system.

UART Mode: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

SPI Mode: The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.



GPIO

The PSoC 4000S has up to 36 GPIOs. The GPIO block implements the following:

- Eight drive modes:
- ☐ Analog input mode (input and output buffers disabled)
- □ Input only
- □ Weak pull-up with strong pull-down
- ☐ Strong pull-up with weak pull-down
- □ Open drain with strong pull-down
- □ Open drain with strong pull-up
- ☐ Strong pull-up with strong pull-down
- □ Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Selectable slew rates for dV/dt related noise control to improve FMI

The pins are organized in logical entities called ports, which are 8-bit in width (less for Ports 2 and 3). During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4000S).

Special Function Peripherals

CapSense

CapSense is supported in the PSoC 4000S through a CapSense Sigma-Delta (CSD) block that can be connected to any pins through an analog multiplex bus via analog switches. CapSense function can thus be provided on any available pin or group of pins in a system under software control. A PSoC Creator component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another analog multiplex bus to provide water-tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input. Proximity sensing can also be implemented.

The CapSense block has two IDACs, which can be used for general purposes if CapSense is not being used (both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

The CapSense block also provides a 10-bit Slope ADC function, which can be used in conjunction with the CapSense function.

The CapSense block is an advanced, low-noise, programmable block with programmable voltage references and current source ranges for improved sensitivity and flexibility. It can also use an external reference voltage. It has a full-wave CSD mode that alternates sensing to VDDA and Ground to null out power-supply related noise.

LCD Segment Drive

The PSoC 4000S has an LCD controller, which can drive up to 8 commons and up to 28 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as Digital Correlation and PWM. Digital Correlation pertains to modulating the frequency and drive levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal to zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays. PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays.



Pinouts

The following table provides the pin list for PSoC 4000S for the 48-pin TQFP, 40-pin QFN, 32-pin QFN, 24-pin QFN, 32-pin TQFP, and 25-ball CSP packages. All port pins support GPIO. Pin 11 is a No-Connect in the 48-TQFP.

Table 1. PSoC 4000S Pin List

48-pin	TQFP	32-pi	n QFN	24-pi	n QFN	25-ba	II CSP	40-pi	n QFN	32-pir	TQFP
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
28	P0.0	17	P0.0	13	P0.0	D1	P0.0	22	P0.0	17	P0.0
29	P0.1	18	P0.1	14	P0.1	C3	P0.1	23	P0.1	18	P0.1
30	P0.2	19	P0.2					24	P0.2	19	P0.2
31	P0.3	20	P0.3					25	P0.3	20	P0.3
32	P0.4	21	P0.4	15	P0.4	C2	P0.4	26	P0.4	21	P0.4
33	P0.5	22	P0.5	16	P0.5	C1	P0.5	27	P0.5	22	P0.5
34	P0.6	23	P0.6	17	P0.6	B1	P0.6	28	P0.6	23	P0.6
35	P0.7					B2	P0.7	29	P0.7		
36	XRES	24	XRES	18	XRES	В3	XRES	30	XRES	24	XRES
37	VCCD	25	VCCD	19	VCCD	A1	VCCD	31	VCCD	25	VCCD
38	VSSD	26	VSSD	20	VSSD	A2	VSS			26	VSSD
39	VDDD	27	VDD	21	VDD	A3	VDD	32	VDDD	27	VDD
40	VDDA	27	VDD	21	VDD	A3	VDD	33	VDDA	27	VDD
41	VSSA	28	VSSA	22	VSSA	A2	VSS	34	VSSA	28	VSSA
42	P1.0	29	P1.0					35	P1.0	29	P1.0
43	P1.1	30	P1.1					36	P1.1	30	P1.1
44	P1.2	31	P1.2	23	P1.2	A4	P1.2	37	P1.2	31	P1.2
45	P1.3	32	P1.3	24	P1.3	B4	P1.3	38	P1.3	32	P1.3
46	P1.4							39	P1.4		
47	P1.5										
48	P1.6										
1	P1.7	1	P1.7	1	P1.7	A5	P1.7	40	P1.7	1	P1.7
2	P2.0	2	P2.0	2	P2.0	B5	P2.0	1	P2.0	2	P2.0
3	P2.1	3	P2.1	3	P2.1	C5	P2.1	2	P2.1	3	P2.1
4	P2.2	4	P2.2					3	P2.2	4	P2.2
5	P2.3	5	P2.3					4	P2.3	5	P2.3
6	P2.4							5	P2.4		
7	P2.5	6	P2.5					6	P2.5	6	P2.5
8	P2.6	7	P2.6	4	P2.6	D5	P2.6	7	P2.6	7	P2.6
9	P2.7	8	P2.7	5	P2.7	C4	P2.7	8	P2.7	8	P2.7
10	VSSD					A2	VSS	9	VSSD		
12	P3.0	9	P3.0	6	P3.0	E5	P3.0	10	P3.0	9	P3.0
13	P3.1	10	P3.1			D4	P3.1	11	P3.1	10	P3.1
14	P3.2	11	P3.2	7	P3.2	E4	P3.2	12	P3.2	11	P3.2
16	P3.3	12	P3.3	8	P3.3	D3	P3.3	13	P3.3	12	P3.3



Table 1. PSoC 4000S Pin List (continued)

48-pin	TQFP	32-pir	n QFN	24-piı	n QFN	25-ba	II CSP	40-pin QFN		32-pin TQFP	
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
17	P3.4							14	P3.4		
18	P3.5							15	P3.5		
19	P3.6							16	P3.6		
20	P3.7							17	P3.7		
21	VDDD										
22	P4.0	13	P4.0	9	P4.0	E3	P4.0	18	P4.0	13	P4.0
23	P4.1	14	P4.1	10	P4.1	D2	P4.1	19	P4.1	14	P4.1
24	P4.2	15	P4.2	11	P4.2	E2	P4.2	20	P4.2	15	P4.2
25	P4.3	16	P4.3	12	P4.3	E1	P4.3	21	P4.3	16	P4.3

Note: Pins 11, 15, 26, and 27 are No connects (NC) on the 48-pin TQFP.

Descriptions of the pin functions are as follows:

 $\boldsymbol{VDDD} :$ Power supply for the digital section.

VDDA: Power supply for the analog section.

VSSD, VSSA: Ground pins for the digital and analog sections respectively.

VCCD: Regulated digital supply (1.8 V ±5%)

VDD: Power supply to all sections of the chip

VSS: Ground for all sections of the chip

Alternate Pin Functions

Each port pin can be assigned to one of multiple functions; it can, for instance, be an analog I/O, a digital peripheral function, an LCD pin, or a CapSense pin. The pin assignments are shown in the following table.

Table 2. Pin Assignments

Port/ Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P0.0	lpcomp.in_p[0]				tcpwm.tr_in[0]		scb[0].spi_select1:0
P0.1	lpcomp.in_n[0]				tcpwm.tr_in[1]		scb[0].spi_select2:0
P0.2	lpcomp.in_p[1]						scb[0].spi_select3:0
P0.3	lpcomp.in_n[1]						
P0.4	wco.wco_in			scb[1].uart_rx:0		scb[1].i2c_scl:0	scb[1].spi_mosi:1
P0.5	wco.wco_out			scb[1].uart_tx:0		scb[1].i2c_sda:0	scb[1].spi_miso:1
P0.6			srss.ext_clk	scb[1].uart_cts:0			scb[1].spi_clk:1
P0.7				scb[1].uart_rts:0			scb[1].spi_select0:1
P1.0			tcpwm.line[2]:1	scb[0].uart_rx:1		scb[0].i2c_scl:0	scb[0].spi_mosi:1
P1.1			tcpwm.line_compl[2]:1	scb[0].uart_tx:1		scb[0].i2c_sda:0	scb[0].spi_miso:1
P1.2			tcpwm.line[3]:1	scb[0].uart_cts:1	tcpwm.tr_in[2]		scb[0].spi_clk:1
P1.3			tcpwm.line_compl[3]:1	scb[0].uart_rts:1	tcpwm.tr_in[3]		scb[0].spi_select0:1
P1.4							scb[0].spi_select1:1

Document Number: 002-00123 Rev. *N Page 12 of 42



Table 2. Pin Assignments (continued)

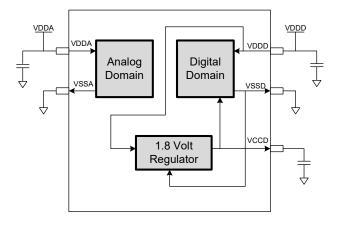
Port/ Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P1.5							scb[0].spi_select2:1
P1.6							scb[0].spi_select3:1
P1.7							
P2.0		prgio[0].io[0]	tcpwm.line[4]:0	csd.comp	tcpwm.tr_in[4]	scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1		prgio[0].io[1]	tcpwm.line_compl[4]:0		tcpwm.tr_in[5]	scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2		prgio[0].io[2]					scb[1].spi_clk:2
P2.3		prgio[0].io[3]					scb[1].spi_select0:2
P2.4		prgio[0].io[4]	tcpwm.line[0]:1				scb[1].spi_select1:1
P2.5		prgio[0].io[5]	tcpwm.line_compl[0]:1				scb[1].spi_select2:1
P2.6		prgio[0].io[6]	tcpwm.line[1]:1				scb[1].spi_select3:1
P2.7		prgio[0].io[7]	tcpwm.line_compl[1]:1			lpcomp.comp[0]:1	
P3.0		prgio[1].io[0]	tcpwm.line[0]:0	scb[1].uart_rx:1		scb[1].i2c_scl:2	scb[1].spi_mosi:0
P3.1		prgio[1].io[1]	tcpwm.line_compl[0]:0	scb[1].uart_tx:1		scb[1].i2c_sda:2	scb[1].spi_miso:0
P3.2		prgio[1].io[2]	tcpwm.line[1]:0	scb[1].uart_cts:1		cpuss.swd_data	scb[1].spi_clk:0
P3.3		prgio[1].io[3]	tcpwm.line_compl[1]:0	scb[1].uart_rts:1		cpuss.swd_clk	scb[1].spi_select0:0
P3.4		prgio[1].io[4]	tcpwm.line[2]:0		tcpwm.tr_in[6]		scb[1].spi_select1:0
P3.5		prgio[1].io[5]	tcpwm.line_compl[2]:0		tcpwm.tr_in[7]		scb[1].spi_select2:0
P3.6		prgio[1].io[6]	tcpwm.line[3]:0		tcpwm.tr_in[8]		scb[1].spi_select3:0
P3.7		prgio[1].io[7]	tcpwm.line_compl[3]:0		tcpwm.tr_in[9]	lpcomp.comp[1]:1	
P4.0	csd.vref_ext			scb[0].uart_rx:0	tcpwm.tr_in[10]	scb[0].i2c_scl:1	scb[0].spi_mosi:0
P4.1	csd.cshieldpads			scb[0].uart_tx:0	tcpwm.tr_in[11]	scb[0].i2c_sda:1	scb[0].spi_miso:0
P4.2	csd.cmodpad			scb[0].uart_cts:0		lpcomp.comp[0]:0	scb[0].spi_clk:0
P4.3	csd.csh_tank			scb[0].uart_rts:0		lpcomp.comp[1]:0	scb[0].spi_select0:0



Power

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4000S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the V_{DD} input.

Figure 4. Power Supply Connections



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is $1.8 \text{ V} \pm 5\%$ (externally regulated; 1.71 to 1.89, internal regulator bypassed).

Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4000S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4000S supplies the internal logic and its output is connected to the V_{CCD} pin. The VCCD pin must be bypassed to ground via an external capacitor (0.1 μ F; X5R ceramic or better) and must not be connected to anything else.

Mode 2: 1.8 V ±5% External Supply

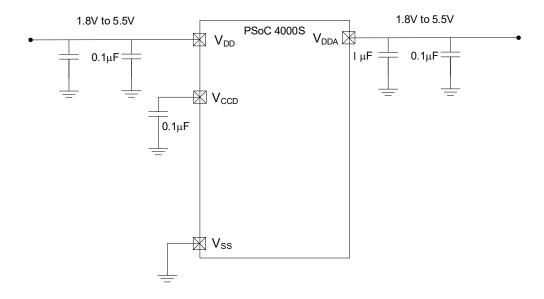
In this mode, the PSoC 4000S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the VDD and VCCD pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from VDDD to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- μ F range, in parallel with a smaller capacitor (0.1 μ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme is shown in the following diagram.

Figure 5. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active

Power supply bypass connections example





Electrical Specifications

Absolute Maximum Ratings

Table 3. Absolute Maximum Ratings^[1]

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID1	V _{DDD_ABS}	Digital supply relative to V _{SS}	-0.5	_	6	V	_
SID2	V _{CCD_ABS}	Direct digital core voltage input relative to V _{SS}	-0.5	-	1.95		_
SID3	V _{GPIO_ABS}	GPIO voltage	-0.5	_	V _{DD} + 0.5		_
SID4	I _{GPIO_ABS}	Maximum current per GPIO	-25	_	25	mA	_
SID5	I _{GPIO_injection}	GPIO injection current, Max for $V_{IH} > V_{DDD}$, and Min for $V_{IL} < V_{SS}$	-0.5	_	0.5		Current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	_	_	V	_
BID45	ESD_CDM	Electrostatic discharge charged device model	500	_	-		_
BID46	LU	Pin current for latch-up	-140	ı	140	mA	_

Note

Document Number: 002-00123 Rev. *N Page 15 of 42

Usage above the absolute maximum conditions listed in Table 3 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended
periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature
Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.



Device Level Specifications

All specifications are valid for –40 °C \leq T_A \leq 105 °C and T_J \leq 125 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 4. DC Specifications

Typical values measured at V_{DD} = 3.3 V and 25 °C.

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID53	V_{DD}	Power supply input voltage	1.8	-	5.5	V	Internally regulated supply
SID255	V_{DD}	Power supply input voltage (V _{CCD} = V _{DD} = V _{DDA})	1.71	_	1.89		Internally unregulated supply
SID54	V _{CCD}	Output voltage (for core logic)	-	1.8	-		_
SID55	C _{EFC}	External regulator voltage bypass	_	0.1	_	μF	X5R ceramic or better
SID56	C _{EXC}	Power supply bypass capacitor	_	1	_		X5R ceramic or better
Active Mode	e, V _{DD} = 1.8 V	to 5.5 V. Typical values measure	d at VDD =	3.3 V and 25	°C.	•	
SID10	I _{DD5}	Execute from flash; CPU at 6 MHz	_	1.2	2.0	mA	_
SID16	I _{DD8}	Execute from flash; CPU at 24 MHz	_	2.4	4.0		_
SID19	I _{DD11}	Execute from flash; CPU at 48 MHz	-	4.6	5.9		_
Sleep Mode	, VDDD = 1.8 '	V to 5.5 V (Regulator on)		I.			
SID22	I _{DD17}	I ² C wakeup WDT, and Comparators on	-	1.1	1.6	mA	6 MHz
SID25	I _{DD20}	I ² C wakeup, WDT, and Comparators on	-	1.4	1.9		12 MHz
Sleep Mode	, V _{DDD} = 1.71	V to 1.89 V (Regulator bypassed)	l .		1	1
SID28	I _{DD23}	I ² C wakeup, WDT, and Comparators on	-	0.7	0.9	mA	6 MHz
SID28A	I _{DD23A}	I ² C wakeup, WDT, and Comparators on	-	0.9	1.1	mA	12 MHz
Deep Sleep	Mode, V _{DD} =	1.8 V to 3.6 V (Regulator on)		I.			
SID31	I _{DD26}	I ² C wakeup and WDT on	-	2.5	60	μA	_
Deep Sleep	Mode, V _{DD} =	3.6 V to 5.5 V (Regulator on)		I.			
SID34	I _{DD29}	I ² C wakeup and WDT on	-	2.5	60	μA	_
Deep Sleep	Mode, V _{DD} =	V _{CCD} = 1.71 V to 1.89 V (Regulate	or bypassed	i)			
SID37	I _{DD32}	I ² C wakeup and WDT on	-	2.5	60	μA	_
XRES Curre	nt				1		•
SID307	I _{DD_XR}	Supply current while XRES asserted	-	2	5	mA	_

Table 5. AC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID48	F _{CPU}	CPU frequency	DC	-	48	MHz	$1.71 \leq V_{DD} \leq 5.5$
SID49 ^[2]	T _{SLEEP}	Wakeup from Sleep mode	_	0	_	μs	_
SID50 ^[2]	T _{DEEPSLEEP}	Wakeup from Deep Sleep mode	_	35	_		_

Note

Document Number: 002-00123 Rev. *N Page 16 of 42

^{2.} Guaranteed by characterization.



GPIO

Table 6. GPIO DC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID57	V _{IH} ^[3]	Input voltage high threshold	$0.7 \times V_{DDD}$	_	_	V	CMOS Input
SID58	V _{IL}	Input voltage low threshold	_	_	$0.3 \times V_{DDD}$		CMOS Input
SID241	V _{IH} ^[3]	LVTTL input, V _{DDD} < 2.7 V	$0.7 \times V_{DDD}$	_	_		_
SID242	V _{IL}	LVTTL input, V _{DDD} < 2.7 V	_	_	$0.3 \times V_{DDD}$		_
SID243	V _{IH} ^[3]	LVTTL input, $V_{DDD} \ge 2.7 \text{ V}$	2.0	_	_		_
SID244	V _{IL}	LVTTL input, $V_{DDD} \ge 2.7 \text{ V}$	_	_	0.8		_
SID59	V _{OH}	Output voltage high level	V _{DDD} – 0.6	_	_		I _{OH} = 4 mA at 3 V V _{DDD}
SID60	V _{OH}	Output voltage high level	V _{DDD} – 0.5	_	-		I _{OH} = 1 mA at 3 V V _{DDD}
SID61	V _{OL}	Output voltage low level	-	_	0.6		I _{OL} = 4 mA at 1.8 V V _{DDD}
SID62	V _{OL}	Output voltage low level	-	-	0.6		I _{OL} = 10 mA at 3 V V _{DDD}
SID62A	V _{OL}	Output voltage low level	-	-	0.4		I _{OL} = 3 mA at 3 V V _{DDD}
SID63	R _{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	-
SID64	R _{PULLDOWN}	Pull-down resistor	3.5	5.6	8.5		_
SID65	I _{IL}	Input leakage current (absolute value)	_	_	2	nA	25 °C, V _{DDD} = 3.0 V
SID66	C _{IN}	Input capacitance	-	_	7	pF	-
SID67 ^[4]	V _{HYSTTL}	Input hysteresis LVTTL	25	40	_	mV	$V_{DDD} \ge 2.7 \text{ V}$
SID68 ^[4]	V _{HYSCMOS}	Input hysteresis CMOS	0.05 × V _{DDD}	_	_		V _{DD} < 4.5 V
SID68A ^[4]	V _{HYSCMOS5V5}	Input hysteresis CMOS	200	_	_		V _{DD} > 4.5 V
SID69 ^[4]	I _{DIODE}	Current through protection diode to V _{DD} /V _{SS}	-	_	100	μA	_
SID69A ^[4]	I _{TOT_GPIO}	Maximum total source or sink chip current	-	_	200	mA	_

V_{IH} must not exceed V_{DDD} + 0.2 V.
 Guaranteed by characterization.



Table 7. GPIO AC Specifications

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID70	T _{RISEF}	Rise time in fast strong mode	2	-	12	ns	3.3 V V _{DDD} , Cload = 25 pF
SID71	T _{FALLF}	Fall time in fast strong mode	2	_	12		3.3 V V _{DDD} , Cload = 25 pF
SID72	T _{RISES}	Rise time in slow strong mode	10	-	60	-	3.3 V V _{DDD} , Cload = 25 pF
SID73	T _{FALLS}	Fall time in slow strong mode	10	-	60	-	3.3 V V _{DDD} , Cload = 25 pF
SID74	F _{GPIOUT1}	$\begin{array}{l} \text{GPIO F}_{\text{OUT}}; 3.3 \text{ V} \! \leq \! \text{V}_{\text{DDD}} \! \leq \! 5.5 \text{ V} \\ \text{Fast strong mode} \end{array}$	_	-	33	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID75	F _{GPIOUT2}	GPIO F _{OUT} ; 1.71 V≤V _{DDD} ≤3.3 V Fast strong mode	_	-	16.7		90/10%, 25 pF load, 60/40 duty cycle
SID76	F _{GPIOUT3}	GPIO F_{OUT} ; 3.3 $V \le V_{DDD} \le 5.5 V$ Slow strong mode	_	-	7		90/10%, 25 pF load, 60/40 duty cycle
SID245	F _{GPIOUT4}	GPIO F_{OUT} ; 1.71 $V \le V_{DDD} \le$ 3.3 V Slow strong mode.	_	-	3.5		90/10%, 25 pF load, 60/40 duty cycle
SID246	F _{GPIOIN}	GPIO input operating frequency; 1.71 V \leq V _{DDD} \leq 5.5 V	_	_	48		90/10% V _{IO}

XRES

Table 8. XRES DC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID77	V_{IH}	Input voltage high threshold	$0.7 \times V_{DDD}$	_	_	V	CMOS Input
SID78	V_{IL}	Input voltage low threshold	_	_	$0.3 \times V_{DDD}$		
SID79	R _{PULLUP}	Pull-up resistor	_	60	-	kΩ	_
SID80	C _{IN}	Input capacitance	_	_	7	pF	_
SID81 ^[5]	V _{HYSXRES}	Input voltage hysteresis	_	100	-	mV	Typical hysteresis is 200 mV for V _{DD} > 4.5 V
SID82	I _{DIODE}	Current through protection diode to V _{DD} /V _{SS}	_	-	100	μA	_

Table 9. XRES AC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID83 ^[5]	T _{RESETWIDTH}	Reset pulse width	1	-	-	μs	_
BID194 ^[5]	T _{RESETWAKE}	Wake-up time from reset release	_	-	2.7	ms	_

Note
5. Guaranteed by characterization.



Analog Peripherals

Comparator

Table 10. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID84	V _{OFFSET1}	Input offset voltage, Factory trim	_	_	±10	mV	_
SID85	V _{OFFSET2}	Input offset voltage, Custom trim	_	_	±4		_
SID86	V _{HYST}	Hysteresis when enabled	_	10	35		_
SID87	V _{ICM1}	Input common mode voltage in normal mode	0	_	V _{DDD} – 0.1	V	Modes 1 and 2
SID247	V _{ICM2}	Input common mode voltage in low power mode	0	_	V_{DDD}		_
SID247A	V _{ICM3}	Input common mode voltage in ultra low power mode	0	_	V _{DDD} – 1.15		V _{DDD} ≥ 2.2 V at –40 °C
SID88	C _{MRR}	Common mode rejection ratio	50	_	_	dB	V _{DDD} ≥ 2.7V
SID88A	C _{MRR}	Common mode rejection ratio	42	_	-		V _{DDD} ≤ 2.7V
SID89	I _{CMP1}	Block current, normal mode	_	_	400	μA	_
SID248	I _{CMP2}	Block current, low power mode	_	_	100		_
SID259	I _{CMP3}	Block current in ultra low-power mode	_	6	28		V _{DDD} ≥ 2.2 V at –40 °C
SID90	Z _{CMP}	DC Input impedance of comparator	35	_	_	МΩ	_

Table 11. Comparator AC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID91		Response time, normal mode, 50 mV overdrive	-	38	110	ns	_
SID258		Response time, low power mode, 50 mV overdrive	-	70	200		_
SID92	TRESP3	Response time, ultra-low power mode, 200 mV overdrive	-	2.3	15	μs	V _{DDD} ≥ 2.2 V at –40 °C

Document Number: 002-00123 Rev. *N Page 19 of 42



CSD and IDAC

Table 12. CSD and IDAC Specifications

SPEC ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	_	_	±50	mV	V _{DD} > 2 V (with ripple), 25 °C T _A , Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	-	-	±25	mV	V_{DD} > 1.75V (with ripple), 25 °C T _A , Parasitic Capacitance (C _P) < 20 pF, Sensitivity \geq 0.4 pF
SID.CSD.BLK	ICSD	Maximum block current	-	-	4000	μΑ	Maximum block current for both IDACs in dynamic (switching) mode including comparators, buffer, and reference generator.
SID.CSD#15	V _{REF}	Voltage reference for CSD and Comparator	0.6	1.2	V _{DDA} - 0.6	V	V _{DDA} – 0.6 or 4.4, whichever is lower
SID.CSD#15A	V _{REF_EXT}	External Voltage reference for CSD and Comparator	0.6	-	V _{DDA} - 0.6	V	V _{DDA} – 0.6 or 4.4, whichever is lower
SID.CSD#16	IDAC1IDD	IDAC1 (7-bits) block current	-	-	1750	μΑ	_
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	_	_	1750	μΑ	-
SID308	VCSD	Voltage range of operation	1.71	-	5.5	٧	1.8 V ±5% or 1.8 V to 5.5 V
SID308A	V _{COMPIDAC}	Voltage compliance range of IDAC	0.6	-	V _{DDA} – 0.6	V	V _{DDA} – 0.6 or 4.4, whichever is lower
SID309	IDAC1DNL	DNL	-1	_	1	LSB	-
SID310	IDAC1INL	INL	-2	-	2	LSB	INL is ±5.5 LSB for V _{DDA} < 2 V
SID311	IDAC2DNL	DNL	-1	_	1	LSB	_
SID312	IDAC2INL	INL	-2	-	2	LSB	INL is ±5.5 LSB for V _{DDA} < 2 V
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	_	_	Ratio	Capacitance range of 5 to 35 pF, 0.1-pF sensitivity. All use cases. V _{DDA} > 2 V.
SID314	IDAC1CRT1	Output current of IDAC1 (7 bits) in low range	4.2	-	5.4	μΑ	LSB = 37.5-nA typ.
SID314A	IDAC1CRT2	Output current of IDAC1(7 bits) in medium range	34	_	41	μΑ	LSB = 300-nA typ.
SID314B	IDAC1CRT3	Output current of IDAC1(7 bits) in high range	275	-	330	μΑ	LSB = 2.4-µA typ.
SID314C	IDAC1CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8	-	10.5	μΑ	LSB = 75-nA typ.
SID314D	IDAC1CRT22	Output current of IDAC1(7 bits) in medium range, 2X mode	69	-	82	μΑ	LSB = 600-nA typ.
SID314E	IDAC1CRT32	Output current of IDAC1(7 bits) in high range, 2X mode	540	_	660	μA	LSB = 4.8-µA typ.
SID315	IDAC2CRT1	Output current of IDAC2 (7 bits) in low range	4.2	-	5.4	μΑ	LSB = 37.5-nA typ.



Table 12. CSD and IDAC Specifications (continued)

SPEC ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID315A	IDAC2CRT2	Output current of IDAC2 (7 bits) in medium range	34	_	41	μA	LSB = 300-nA typ.
SID315B	IDAC2CRT3	Output current of IDAC2 (7 bits) in high range	275	1	330	μA	LSB = 2.4-µA typ.
SID315C	IDAC2CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8	_	10.5	μA	LSB = 75-nA typ.
SID315D	IDAC2CRT22	Output current of IDAC2(7 bits) in medium range, 2X mode	69	_	82	μA	LSB = 600-nA typ.
SID315E	IDAC2CRT32	Output current of IDAC2(7 bits) in high range, 2X mode	540	_	660	μA	LSB = 4.8-µA typ.
SID315F	IDAC3CRT13	Output current of IDAC in 8-bit mode in low range	8	_	10.5	μA	LSB = 37.5-nA typ.
SID315G	IDAC3CRT23	Output current of IDAC in 8-bit mode in medium range	69	_	82	μA	LSB = 300-nA typ.
SID315H	IDAC3CRT33	Output current of IDAC in 8-bit mode in high range	540	_	660	μA	LSB = 2.4-µA typ.
SID320	IDACOFFSET	All zeroes input	-	-	1	LSB	Polarity set by Source or Sink. Offset is 2 LSBs for 37.5 nA/LSB mode
SID321	IDACGAIN	Full-scale error less offset	_	_	±10	%	_
SID322	IDACMISMATCH1	Mismatch between IDAC1 and IDAC2 in Low mode	_	_	9.2	LSB	LSB = 37.5-nA typ.
SID322A	IDACMISMATCH2	Mismatch between IDAC1 and IDAC2 in Medium mode	_	_	5.6	LSB	LSB = 300-nA typ.
SID322B	IDACMISMATCH3	Mismatch between IDAC1 and IDAC2 in High mode	_	_	6.8	LSB	LSB = 2.4-µA typ.
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	_	_	10	μs	Full-scale transition. No external load.
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	-	_	10	μs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor.	_	2.2	_	nF	5-V rating, X7R or NP0 cap.

Document Number: 002-00123 Rev. *N Page 21 of 42



10-bit CapSense ADC

Table 13. 10-bit CapSense ADC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SIDA94	A_RES	Resolution	-	_	10	bits	Auto-zeroing is required every millisecond
SIDA95	A_CHNLS_S	Number of channels - single ended	_	_	16		Defined by AMUX Bus.
SIDA97	A-MONO	Monotonicity	_	-	_	Yes	_
SIDA98	A_GAINERR	Gain error	-	_	±2	%	In V_{REF} (2.4 V) mode with V_{DDA} bypass capacitance of 10 μF
SIDA99	A_OFFSET	Input offset voltage	-	_	3	mV	In V _{REF} (2.4 V) mode with V _{DDA} bypass capacitance of 10 μF
SIDA100	A_ISAR	Current consumption	_	-	0.25	mA	-
SIDA101	A_VINS	Input voltage range - single ended	V_{SSA}	_	V_{DDA}	V	_
SIDA103	A_INRES	Input resistance	_	2.2	_	ΚΩ	-
SIDA104	A_INCAP	Input capacitance	_	20	_	pF	-
SIDA106	A_PSRR	Power supply rejection ratio	-	60	-	dB	In V _{REF} (2.4 V) mode with V _{DDA} bypass capacitance of 10 μF
SIDA107	A_TACQ	Sample acquisition time	_	1	_	μs	_
SIDA108	A_CONV8	Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.	-	-	21.3	μs	Does not include acquisition time. Equivalent to 44.8 ksps including acquisition time.
SIDA108A	A_CONV10	Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.	-	-	85.3	μs	Does not include acquisition time. Equivalent to 11.6 ksps including acquisition time.
SIDA109	A_SND	Signal-to-noise and Distortion ratio (SINAD)	-	61	_	dB	With 10-Hz input sine wave, external 2.4-V reference, V _{REF} (2.4 V) mode
SIDA110	A_BW	Input bandwidth without aliasing	_	-	22.4	kHz	8-bit resolution
SIDA111	A_INL	Integral Non Linearity. 1 ksps	_	_	2	LSB	V _{REF} = 2.4 V or greater
SIDA112	A_DNL	Differential Non Linearity. 1 ksps	_	-	1	LSB	_



Digital Peripherals

Timer Counter Pulse-Width Modulator (TCPWM)

Table 14. TCPWM Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID.TCPWM.1	ITCPWM1	Block current consumption at 3 MHz	_	_	45	μA	All modes (TCPWM)
SID.TCPWM.2	ITCPWM2	Block current consumption at 12 MHz	_	_	155		All modes (TCPWM)
SID.TCPWM.2A	ITCPWM3	Block current consumption at 48 MHz	_	_	650		All modes (TCPWM)
SID.TCPWM.3	TCPWM _{FREQ}	Operating frequency	-	_	Fc	MHz	Fc max = CLK_SYS Maximum = 48 MHz
SID.TCPWM.4	TPWM _{ENEXT}	Input trigger pulse width	2/Fc	_	_	ns	For all trigger events ^[6]
SID.TCPWM.5	TPWM _{EXT}	Output trigger pulse widths	2/Fc	-	-		Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) outputs
SID.TCPWM.5A	TC _{RES}	Resolution of counter	1/Fc	_	_		Minimum time between successive counts
SID.TCPWM.5B	PWM _{RES}	PWM resolution	1/Fc	_	_		Minimum pulse width of PWM Output
SID.TCPWM.5C	Q _{RES}	Quadrature inputs resolution	1/Fc	_	_		Minimum pulse width between Quadrature phase inputs

Document Number: 002-00123 Rev. *N Page 23 of 42

Note6. Trigger events can be Stop, Start, Reload, Count, Capture, or Kill depending on which mode of operation is selected.



РC

Table 15. Fixed I²C DC Specifications^[7]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID149	I _{I2C1}	Block current consumption at 100 kHz	_	_	50	μΑ	_
SID150	I _{I2C2}	Block current consumption at 400 kHz	_	_	135		_
SID151	I _{I2C3}	Block current consumption at 1 Mbps	_	_	310		_
SID152	I _{I2C4}	I ² C enabled in Deep Sleep mode	ı	ı	1.4		_

Table 16. Fixed I²C AC Specifications^[7]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID153	F _{I2C1}	Bit rate	_	-	1	Msps	_

SPI

Table 17. SPI DC Specifications^[7]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID163	ISPI1	Block current consumption at 1 Mbps	_	_	360	μA	-
SID164	ISPI2	Block current consumption at 4 Mbps	_	_	560		-
SID165	ISPI3	Block current consumption at 8 Mbps	_	_	600		-

Table 18. SPI AC Specifications^[7]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID166	FSPI	SPI operating frequency (Master; 6X Oversampling)	-	_	8	MHz	_
Fixed SPI M	laster Mode AC	Specifications					
SID167	TDMO	MOSI Valid after SClock driving edge	_	_	15	ns	_
SID168	TDSI	MISO Valid before SClock capturing edge	20	_	_		Full clock, late MISO sampling
SID169	THMO	Previous MOSI data hold time	0	_	_		Referred to Slave capturing edge
Fixed SPI S	lave Mode AC S	pecifications					
SID170	TDMI	MOSI Valid before Sclock Capturing edge	40	_	_	ns	_
SID171	TDSO	MISO Valid after Sclock driving edge	_	_	42 + (3 × Tcpu)		T _{CPU} = 1/F _{CPU}
SID171A	TDSO_EXT	MISO Valid after Sclock driving edge in Ext. Clk mode	_	_	48		_
SID172	THSO	Previous MISO data hold time	0	_	_		-
SID172A	TSSELSSCK	SSEL Valid to first SCK Valid edge	100	-	-	ns	_

Note
7. Guaranteed by characterization.



UART

Table 19. UART DC Specifications^[8]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID160	I _{UART1}	Block current consumption at 100 Kbps	-	ı	55	μA	_
SID161	I _{UART2}	Block current consumption at 1000 Kbps	_	-	312	μA	_

Table 20. UART AC Specifications^[8]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID162	F _{UART}	Bit rate	-	-	1	Mbps	_

LCD Direct Drive

Table 21. LCD Direct Drive DC Specifications $^{[8]}$

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID154	I _{LCDLOW}	Operating current in low power mode	-	5	-	μA	16 × 4 small segment disp. at 50 Hz
SID155	C _{LCDCAP}	LCD capacitance per segment/common driver	-	500	5000	pF	_
SID156	LCD _{OFFSET}	Long-term segment offset	-	20	-	mV	_
SID157	I _{LCDOP1}	LCD system operating current Vbias = 5 V	_	2	_	mA	32 × 4 segments. 50 Hz. 25 °C
SID158	I _{LCDOP2}	LCD system operating current Vbias = 3.3 V	-	2	1		32 × 4 segments. 50 Hz. 25 °C

Table 22. LCD Direct Drive AC Specifications^[8]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID159	F _{LCD}	LCD frame rate	10	50	150	Hz	_

Note8. Guaranteed by characterization.



Memory

Flash

Table 23. Flash DC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID173	V_{PE}	Erase and program voltage	1.71	-	5.5	V	_

Table 24. Flash AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID174	T _{ROWWRITE} ^[9]	Row (block) write time (erase and program)	_	_	20	ms	Row (block) = 128 bytes
SID175	T _{ROWERASE} ^[9]	Row erase time	_	_	16		_
SID176	T _{ROWPROGRAM} ^[9]	Row program time after erase	_	_	4		_
SID178	T _{BULKERASE} ^[9]	Bulk erase time (32 KB)	_	-	35		_
SID180 ^[10]	T _{DEVPROG} ^[9]	Total device program time	_	_	7	Seconds	-
SID181 ^[10]	F _{END}	Flash endurance	100 K	_	_	Cycles	_
[40]	F _{RET}	Flash retention. T _A ≤ 55 °C, 100 K P/E cycles.	20	_	-	Years	_
SID182A ^[10]		Flash retention. T _A ≤ 85 °C, 10 K P/E cycles.	10	_	-		_
SID182B ^[10]	F _{RETQ}	Flash retention. T _A ≤ 105 °C, 10 K P/E cycles, ≤ three years at T _A ≥ 85 °C.	10	_	20		Guaranteed by Characterization
SID256	TWS48	Number of Wait states at 48 MHz	2	_	-		CPU execution from Flash
SID257	TWS24	Number of Wait states at 24 MHz	1	_	_		CPU execution from Flash

System Resources

Power-on Reset (POR)

Table 25. Power On Reset (PRES)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID.CLK#6	SR_POWER_UP	Power supply slew rate	1	1	67		At power-up and power-down
SID185 ^[10]	V _{RISEIPOR}	Rising trip voltage	0.80	1	1.5	V	_
SID186 ^[10]	V _{FALLIPOR}	Falling trip voltage	0.70	-	1.4		_

Table 26. Brown-out Detect (BOD) for V_{CCD}

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID190 ^[10]	V _{FALLPPOR}	BOD trip voltage in active and sleep modes	1.48	I	1.62	V	_
SID192 ^[10]	V _{FALLDPSLP}	BOD trip voltage in Deep Sleep	1.11	-	1.5		_

Notes

It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations may be interrupted and cannot be relied
on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs.
Make certain that these are not inadvertently activated.

^{10.} Guaranteed by characterization.

Page 27 of 42



SWD Interface

Table 27. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID213	F_SWDCLK1	$3.3~V \le V_{DD} \le 5.5~V$	_	-	14		SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	$1.71 \text{ V} \le \text{V}_{DD} \le 3.3 \text{ V}$	_	_	7		SWDCLK ≤ 1/3 CPU clock frequency
SID215 ^[11]	T_SWDI_SETUP	T = 1/f SWDCLK	0.25 × T	_	_	ns	_
SID216 ^[11]	T_SWDI_HOLD	T = 1/f SWDCLK	0.25 × T	_	_		_
SID217 ^[11]	T_SWDO_VALID	T = 1/f SWDCLK	_	_	0.5 × T		_
SID217A ^[11]	T_SWDO_HOLD	T = 1/f SWDCLK	1	_	_		_

Internal Main Oscillator (IMO)

Table 28. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID218	I _{IMO1}	IMO operating current at 48 MHz	-	-	250	μA	_
SID219	I _{IMO2}	IMO operating current at 24 MHz	_	_	180	μA	_

Table 29. IMO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID223	IIVIOTOLI	Frequency variation at 24, 32,	_	-	±2	%	_
SID223A		and 48 MHz (trimmed)	_	_	±2.5	%	105 °C
SID226	T _{STARTIMO}	IMO startup time	_	_	7	μs	_
SID228	T _{JITRMSIMO2}	RMS jitter at 24 MHz	_	145	_	ps	_

Internal Low-Speed Oscillator (ILO)

Table 30. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID231 ^[11]	I _{ILO1}	ILO operating current	-	0.3	1.05	μA	_

Table 31. ILO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID234 ^[11]	T _{STARTILO1}	ILO startup time	_	1	2	ms	_
SID236 ^[11]	T _{ILODUTY}	ILO duty cycle	40	50	60	%	_
SID237	F _{ILOTRIM1}	ILO frequency range	20	40	80	kHz	_

Note 11. Guaranteed by characterization.



Watch Crystal Oscillator (WCO)

Table 32. Watch Crystal Oscillator (WCO) Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID398	FWCO	Crystal Frequency	_	32.768	_	kHz	_
SID399	FTOL	Frequency tolerance	-	50	250	ppm	With 20-ppm crystal
SID400	ESR	Equivalent series resistance	-	50	_	kΩ	_
SID401	PD	Drive Level	_	_	1	μW	_
SID402	TSTART	Startup time	_	_	500	ms	_
SID403	CL	Crystal Load Capacitance	6	_	12.5	pF	_
SID404	C0	Crystal Shunt Capacitance	-	1.35	_	pF	_
SID405	IWCO1	Operating Current (high power mode)	-	_	8	μA	_
SID406	IWCO2	Operating Current (low power mode)	_	ı	1	μA	_

External Clock

Table 33. External Clock Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
	ExtClkFreq	External clock input frequency	0	_	48	MHz	_
SID306 ^[12]	ExtClkDuty	Duty cycle; measured at V _{DD/2}	45	_	55	%	_

Clock

Table 34. Clock Specs

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID262 ^[12]	T _{CLKSWITCH}	System clock source switching time	3	-	4	Periods	_

Smart I/O Pass-through Time

Table 35. Smart I/O Pass-through Time (Delay in Bypass Mode)

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID252	PRG_BYPASS	Max delay added by Smart I/O in	_	-	1.6	ns	_
		bypass mode					

Note 12. Guaranteed by characterization.



Ordering Information

The PSoC 4000S part numbers and features are listed in the following table.

Table 36. PSoC 4000S Ordering Information

							Featu	ıres								Pac	kage	1		
Category	MPN	Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	Opamp (CTBm)	CapSense	10-bit CSD ADC	12-bit SAR ADC	LP Comparators	TCPWM Blocks	SCB Blocks	Smart I/Os	GPIO	WLCSP (0.35-mm pitch)	24-pin QFN	32-pin QFN	32-pin TQFP	40-pin QFN	48-pin TQFP	Temperature Range
	CY8C4024FNI-S402	24	16	2	0	0	1	0	2	5	2	8	21	٧						
	CY8C4024LQI-S401	24	16	2	0	0	1	0	2	5	2	8	19		~					
	CY8C4024LQI-S402	24	16	2	0	0	1	0	2	5	2	16	27			~				
	CY8C4024AXI-S402	24	16	2	0	0	1	0	2	5	2	16	27				~			
	CY8C4024LQI-S403	24	16	2	0	0	1	0	2	5	2	16	34					~		
	CY8C4024AZI-S403	24	16	2	0	0	1	0	2	5	2	16	36						~	–40 to 85 °C
4024	CY8C4024FNI-S412	24	16	2	0	1	1	0	2	5	2	8	21	'						10 10 00 0
	CY8C4024LQI-S411	24	16	2	0	1	1	0	2	5	2	8	19		~					
	CY8C4024LQI-S412	24	16	2	0	1	1	0	2	5	2	16	27			~				
	CY8C4024AXI-S412	24	16	2	0	1	1	0	2	5	2	16	27				~			
	CY8C4024LQI-S413	24	16	2	0	1	1	0	2	5	2	16	34					~		
	CY8C4024AZI-S413	24	16	2	0	1	1	0	2	5	2	16	36						~	
	CY8C4024AZQ-S413	24	16	2	0	1	1	0	2	5	2	16	36						~	–40 to 105 °C
	CY8C4025FNI-S402	24	32	4	0	0	1	0	2	5	2	8	21	~						
	CY8C4025LQI-S401	24	32	4	0	0	1	0	2	5	2	8	19		~					
	CY8C4025LQI-S402	24	32	4	0	0	1	0	2	5	2	16	27			~				–40 to 85 °C
	CY8C4025AXI-S402	24	32	4	0	0	1	0	2	5	2	16	27				~			40 10 00 0
	CY8C4025LQI-S403	24	32	4	0	0	1	0	2	5	2	16	34					~		
	CY8C4025AZI-S403	24	32	4	0	0	1	0	2	5	2	16	36						~	
	CY8C4025AZQ-S403	24	32	4	0	0	1	0	2	5	2	16	36						~	–40 to 105 °C
4025	CY8C4025FNI-S412	24	32	4	0	1	1	0	2	5	2	8	21	~						
	CY8C4025LQI-S411	24	32	4	0	1	1	0	2	5	2	8	19		~					
	CY8C4025LQI-S412	24	32	4	0	1	1	0	2	5	2	16	27			~				
	CY8C4025AXI-S412	24	32	4	0	1	1	0	2	5	2	16	27				~			–40 to 85 °C
	CY8C4025LQI-S413	24	32	4	0	1	1	0	2	5	2	16	34					~		
	CY8C4025AZI-S413	24	32	4	0	1	1	0	2	5	2	16	36						~	–40 to 105 °C
	CY8C4025AZQ-S413	24	32	4	0	1	1	0	2	5	2	16	36						~	
	CY8C4045FNI-S412	48	32	4	0	1	1	0	2	5	2	8	21	~						
	CY8C4045LQI-S411	48	32	4	0	1	1	0	2	5	2	8	19		~					
	CY8C4045LQI-S412	48	32	4	0	1	1	0	2	5	2	16	27			~				
4045	CY8C4045AXI-S412	48	32	4	0	1	1	0	2	5	2	16	27				~			
	CY8C4045LQI-S413	48	32	4	0	1	1	0	2	5	2	16	34					~		
	CY8C4045AZI-S413	48	32	4	0	1	1	0	2	5	2	16	36						V	
	CY8C4045AZQ-S413	48	32	4	0	1	1	0	2	5	2	16	36						~	

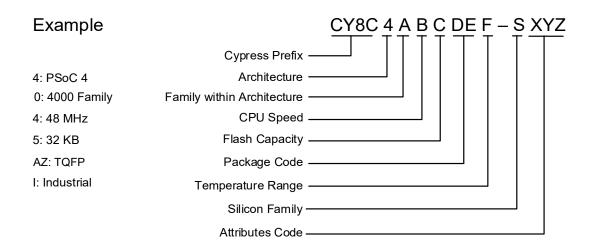


The nomenclature used in the preceding table is based on the following part numbering convention:

Table 37. Nomenclature

Field	Description	Values	Meaning		
CY8C	Cypress Prefix				
4	Architecture	4	PSoC 4		
Α	Family	0	4000 Family		
В	CPU Speed	2	24 MHz		
		4	48 MHz		
С	Flash Capacity	4	16 KB		
		5	32 KB		
		6	64 KB		
		7	128 KB		
DE	Package Code	AX	TQFP (0.8-mm pitch)		
		AZ	TQFP (0.5-mm pitch)		
		LQ	QFN		
		PV	SSOP		
		FN	CSP		
F	Temperature Range	Ĺ	Industrial		
		Q	Extended Industrial		
S	Series Designator	S	PSoC 4 S-Series		
		М	PSoC 4 M-Series		
		L	PSoC 4 L-Series		
		BL	PSoC 4 BLE-Series		
XYZ	Attributes Code	000-999	Code of feature set in the specific family		

The following is an example of a part number:





Packaging

The PSoC 4000S is offered in 48-pin TQFP, 40-pin QFN, 32-pin QFN, 32-pin QFN, 32-pin TQFP, and 25-ball WLCSP packages. Package dimensions and Cypress drawing numbers are in the following table.

Table 38. Package List

Spec ID#	Package	Description	Package Dwg
BID20	48-pin TQFP	7 × 7 × 1.4 mm height with 0.5-mm pitch	51-85135
BID27	40-pin QFN	6 × 6 × 0.6 mm height with 0.5-mm pitch	001-80659
BID34A	32-pin QFN	5 × 5 × 0.6 mm height with 0.5-mm pitch	001-42168
BID34	24-pin QFN	4 × 4 × 0.6 mm height with 0.5-mm pitch	001-13937
BID34G	32-pin TQFP	7 × 7 × 1.4 mm height with 0.8-mm pitch	51-85088
BID34F	25-ball WLCSP	2.02 × 1.93 × 0.48 mm height with 0.35-mm pitch	002-09957

Table 39. Package Thermal Characteristics

Parameter	Description	Package	Min	Тур	Max	Units
TA	Operating ambient temperature	-	-40	25	105	°C
TJ	Operating junction temperature	-	-40	_	125	°C
TJA	Package θ _{JA}	48-pin TQFP	-	73.5	_	°C/W
TJC	Package θ _{JC}	48-pin TQFP	-	33.5	_	°C/W
TJA	Package θ _{JA}	40-pin QFN	_	17.8	_	°C/W
TJC	Package θ_{JC}	40-pin QFN	_	2.8	_	°C/W
TJA	Package θ _{JA}	32-pin QFN	-	20.8	_	°C/W
TJC	Package θ_{JC}	32-pin QFN	_	5.9	_	°C/W
TJA	Package θ _{JA}	24-pin QFN	-	21.7	_	°C/W
TJC	Package θ_{JC}	24-pin QFN	_	5.6	_	°C/W
TJA	Package θ_{JA}	32-pin TQFP	_	29.4	_	°C/W
TJC	Package θ_{JC}	32-pin TQFP	_	3.5	_	°C/W
TJA	Package θ _{JA}	25-ball WLCSP	_	40	_	°C/W
TJC	Package θ_{JC}	25-ball WLCSP	-	0.5	_	°C/W

Table 40. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All	260 °C	30 seconds

Table 41. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-020

_	
Package	MSL
All except WLCSP	MSL 3
25-ball WLCSP	MSL 1

Document Number: 002-00123 Rev. *N Page 31 of 42



Package Diagrams

Figure 6. 48-pin TQFP (7 × 7 × 1.4 mm) Package Outline, 51-85135

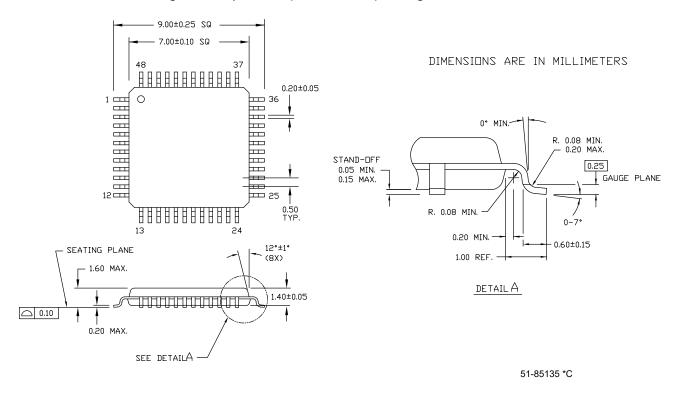
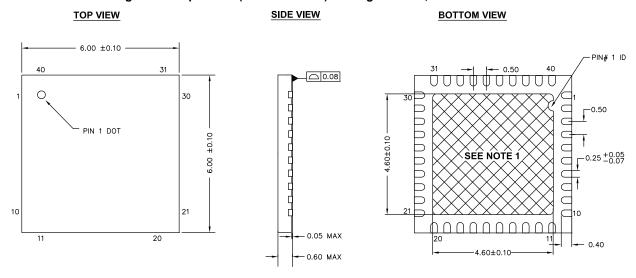


Figure 7. 40-pin QFN (6 × 6 × 0.6 mm) Package Outline, 001-80659



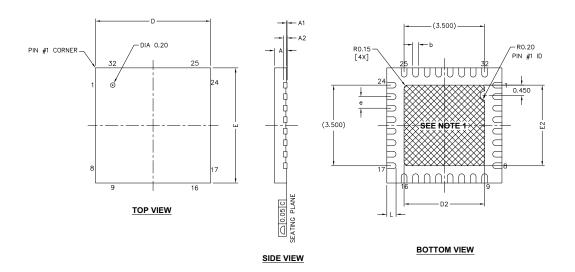
NOTES:

- 2. REFERENCE JEDEC # MO-248
- 3. PACKAGE WEIGHT: 68 ±2 mg
- 4. ALL DIMENSIONS ARE IN MILLIMETERS

001-80659 *A



Figure 8. 32-pin QFN ((5.0 × 5.0 × 0.55 mm) 3.5 × 3.5 mm E-Pad (Sawn)) Package Outline, 001-42168



SYMBOL	D	IMENSIC	NS			
STWIBOL	MIN.	NOM.	MAX.			
Α	0.50	0.55	0.60			
A1	-	0.020	0.045			
A2	0.15 BSC					
D	4.90	5.00	5.10			
D2	3.40	3.50	3.60			
E	4.90	5.00	5.10			
E2	3.40	3.50	3.60			
L	0.30	0.40	0.50			
b	0.18	0.25	0.30			
е	0.50 TYP					

NOTES:

- 1. HATCH AREA IS SOLDERABLE EXPOSED PAD
- 2. BASED ON REF JEDEC # MO-248
- 3. PACKAGE WEIGHT: 0.0388g
- 4. DIMENSIONS ARE IN MILLIMETERS

001-42168 *F



TOP VIEW SIDE VIEW BOTTOM VIEW 4.00±0.10 24 19 PIN# 1 ID 19 24 18 0.50<u>+</u>0.05 PIN 1 DOT 4.00±0.10 -2.65 ± 0.10 13 6 0.25<u>+</u>0.07 12 0.05 MAX 0.60 MAX -0.40±0.10 - 2.65±0.10 -△ 0.08 0.550-

Figure 9. 24-pin QFN ((4 × 4 × 0.60 mm) 2.65 × 2.65 E-Pad (Sawn)) Package Outline, 001-13937

NOTES:

- 1. HATCH IS SOLDERABLE EXPOSED METAL.
- 2. REFERENCE JEDEC # MO-248
- 3. PACKAGE WEIGHT: $29 \pm 3 \text{ mg}$
- 4. ALL DIMENSIONS ARE IN MILLIMETERS

001-13937 *H

The center pad on the QFN package should be connected to ground (VSS) for best mechanical, thermal, and electrical performance. If not connected to ground, it should be electrically floating and not connected to any other signal.

Figure 10. 32-pin TQFP (7 × 7 × 1.4 mm) Package Outline, 51-85088

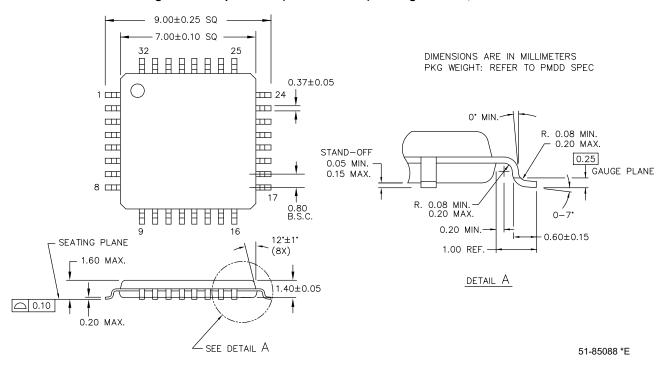
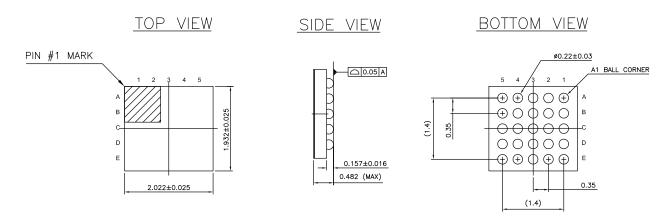




Figure 11. 25-ball WLCSP (2.02 × 1.93 × 0.48 mm) Package Outline, 002-09957



ALL DIMENSIONS ARE IN MM JEDEC Publication 95; Design Guide 4.18

002-09957 **



Acronyms

Table 42. Acronyms Used in this Document

Acronym	Description
abus	analog local bus
ADC	analog-to-digital converter
AG	analog global
AHB	
АПВ	AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus
ALU	arithmetic logic unit
AMUXBUS	analog multiplexer bus
API	application programming interface
APSR	application program status register
ARM [®]	advanced RISC machine, a CPU architecture
ATM	automatic thump mode
BW	bandwidth
CAN	Controller Area Network, a communications protocol
CMRR	common-mode rejection ratio
CPU	central processing unit
CRC	cyclic redundancy check, an error-checking protocol
DAC	digital-to-analog converter, see also IDAC, VDAC
DFB	digital filter block
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.
DMIPS	Dhrystone million instructions per second
DMA	direct memory access, see also TD
DNL	differential nonlinearity, see also INL
DNU	do not use
DR	port write data registers
DSI	digital system interconnect
DWT	data watchpoint and trace
ECC	error correcting code
ECO	external crystal oscillator
EEPROM	electrically erasable programmable read-only memory
EMI	electromagnetic interference
EMIF	external memory interface
EOC	end of conversion
EOF	end of frame
EPSR	execution program status register
ESD	electrostatic discharge

Table 42. Acronyms Used in this Document (continued)

Acronym	Description	
ETM	embedded trace macrocell	
FIR	finite impulse response, see also IIR	
FPB	flash patch and breakpoint	
FS	full-speed	
GPIO	general-purpose input/output, applies to a PSoC pin	
HVI	high-voltage interrupt, see also LVI, LVD	
IC	integrated circuit	
IDAC	current DAC, see also DAC, VDAC	
IDE	integrated development environment	
I ² C, or IIC	Inter-Integrated Circuit, a communications protocol	
IIR	infinite impulse response, see also FIR	
ILO	internal low-speed oscillator, see also IMO	
IMO	internal main oscillator, see also ILO	
INL	integral nonlinearity, see also DNL	
I/O	input/output, see also GPIO, DIO, SIO, USBIO	
IPOR	initial power-on reset	
IPSR	interrupt program status register	
IRQ	interrupt request	
ITM	instrumentation trace macrocell	
LCD	liquid crystal display	
LIN	Local Interconnect Network, a communications protocol.	
LR	link register	
LUT	lookup table	
LVD	low-voltage detect, see also LVI	
LVI	low-voltage interrupt, see also HVI	
LVTTL	low-voltage transistor-transistor logic	
MAC	multiply-accumulate	
MCU	microcontroller unit	
MISO	master-in slave-out	
NC	no connect	
NMI	nonmaskable interrupt	
NRZ	non-return-to-zero	
NVIC	nested vectored interrupt controller	
NVL	nonvolatile latch, see also WOL	
opamp	operational amplifier	
PAL	programmable array logic, see also PLD	
PC	program counter	
PCB	printed circuit board	

Document Number: 002-00123 Rev. *N Page 36 of 42



Table 42. Acronyms Used in this Document (continued)

Acronym	Description	
PGA	programmable gain amplifier	
PHUB	peripheral hub	
PHY	physical layer	
PICU	port interrupt control unit	
PLA	programmable logic array	
PLD	programmable logic device, see also PAL	
PLL	phase-locked loop	
PMDD	package material declaration datasheet	
POR	power-on reset	
PRES	precise power-on reset	
PRS	pseudo random sequence	
PS	port read data register	
PSoC [®]	Programmable System-on-Chip™	
PSRR	power supply rejection ratio	
PWM	pulse-width modulator	
RAM	random-access memory	
RISC	reduced-instruction-set computing	
RMS	root-mean-square	
RTC	real-time clock	
RTL	register transfer language	
RTR	remote transmission request	
RX	receive	
SAR	successive approximation register	
SC/CT	switched capacitor/continuous time	
SCL	I ² C serial clock	
SDA	I ² C serial data	
S/H	sample and hold	
SINAD	signal to noise and distortion ratio	
SIO	special input/output, GPIO with advanced features. See GPIO.	
SOC	start of conversion	
SOF	start of frame	
SPI	Serial Peripheral Interface, a communications protocol	
SR	slew rate	
SRAM	static random access memory	
SRES	software reset	
SWD	serial wire debug, a test protocol	
SWV	single-wire viewer	
TD	transaction descriptor, see also DMA	

Table 42. Acronyms Used in this Document (continued)

Acronym	Description
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

Document Number: 002-00123 Rev. *N Page 37 of 42



Document Conventions

Units of Measure

Table 43. Units of Measure

Table 43. Units of Measure			
Symbol	Unit of Measure		
°C	degrees Celsius		
dB	decibel		
fF	femto farad		
Hz	hertz		
KB	1024 bytes		
kbps	kilobits per second		
Khr	kilohour		
kHz	kilohertz		
kΩ	kilo ohm		
ksps	kilosamples per second		
LSB	least significant bit		
Mbps	megabits per second		
MHz	megahertz		
ΜΩ	mega-ohm		
Msps	megasamples per second		
μΑ	microampere		
μF	microfarad		
μH	microhenry		
μs	microsecond		
μV	microvolt		
μW	microwatt		
mA	milliampere		
ms	millisecond		
mV	millivolt		
nA	nanoampere		
ns	nanosecond		
nV	nanovolt		
Ω	ohm		
pF	picofarad		
ppm	parts per million		
ps	picosecond		
s	second		
sps	samples per second		
sqrtHz	square root of hertz		
V	volt		
I .	I.		



Document History Page

Revision 1	Number: 00	Submission Date	Description of Change
**	4883809	08/28/2015	New data sheet.
*A	4992376	10/30/2015	Removed 20-ball WLCSP package related information in all instances across the document Added 25-ball WLCSP package related information in all instances across the document. Updated Pinouts: Updated Table 1. Updated Electrical Specifications: Updated Analog Peripherals: Updated Comparator: Updated Table 10 (Updated details in "Details/Conditions" column corresponding to V_{ICM3} : I_{CMP3} parameters (Added $V_{DDD} \ge 2.2V$ at -40 °C)). Updated Table 11 (Updated details in "Details/Conditions" column corresponding to TRESP3 parameter (Added $V_{DDD} \ge 2.2V$ at -40 °C)). Updated CSD and IDAC: Updated Table 13. Updated Ordering Information: Updated part numbers.
*B	5037826	12/08/2015	Changed status from Advance to Preliminary.
*C	5104369	01/27/2016	Updated Packaging: Updated Table 39 (Replaced TBD with values for Theta J _A and Theta J _C parameters). Updated Package Diagrams: Replaced TBD with spec 002-09957 **. Added Errata.
*D	5139206	02/16/2016	Updated to new template.
*E	5173961	03/15/2016	Updated Pinouts: Updated Table 1. Updated Electrical Specifications: Updated Device Level Specifications: Updated XRES: Updated Table 8 (Updated all values corresponding to R _{PULLUP} parameter). Updated Table 9 (Updated all values corresponding to T _{RESETWAKE} parameter). Updated Analog Peripherals: Updated CSD and IDAC: Updated Table 12. Updated Table 12. Updated 10-bit CapSense ADC: Updated Table 13. Updated Memory: Updated Flash: Updated Flash: Updated Table 24 (Updated all values corresponding to T _{ROWERASE} , T _{ROWPROGRAM} parameters).
*F	5268662	05/12/2016	Updated Pinouts: Updated Alternate Pin Functions: Updated Table 2. Updated Electrical Specifications: Updated Analog Peripherals: Updated CSD and IDAC: Updated Table 12 (Updated all values corresponding to IDAC1INL, IDAC2INL, SNR, IDAC1CRT1, IDAC1CRT12, IDAC1CRT22, IDAC1CRT32, IDAC2CRT1, IDAC2CRT12, IDAC2CRT22, IDAC2CRT32, IDAC3CRT32, IDAC3



Document History Page (continued)

Description Title: PSoC 4: PSoC 4000S Datasheet, Programmable System-on-Chip (PSoC) Document Number: 002-00123			
Revision	ECN	Submission Date	Description of Change
*G	5330930	07/27/2016	Changed status from Preliminary to Final. Updated Functional Definition: Updated Special Function Peripherals: Updated LCD Segment Drive: Updated description. Updated Electrical Specifications: Updated Device Level Specifications: Updated Table 4 (Updated details corresponding to I _{DD5} , I _{DD8} , I _{DD11} , I _{DD17} , I _{DD20} , I _{DD23} , I _{DD23} , I _{DD29} , I _{DD29} , I _{DD2}
*H	5415365	09/14/2016	Added 40-pin QFN package related information in all instances across the document. Updated Electrical Specifications: Updated Device Level Specifications: Updated Table 4 (Updated details corresponding to I _{DD5} , I _{DD8} , I _{DD11} , I _{DD17} , I _{DD20} , I _{DD23} , I _{DD23} , I _{DD29} , I _{DD32} , I _{DD28} , I _{DD29} , I _{DD32} , I _{DD2NR} parameters). Updated Packaging: Updated Package Diagrams: Added spec 001-80659 *A.
*	5561833	01/09/2017	Updated Electrical Specifications: Replaced PRGIO with Smart I/O in all instances.
*J	5704046	04/26/2017	Updated the Cypress Logo and Copyright.
*K	5969745	11/17/2017	Updated Document Title to read as "PSoC® 4: PSoC 4000S Datasheet Programmable System-on-Chip (PSoC®)". Added 32-pin TQFP Package related information in all instance across the document. Updated Ordering Information: Updated part numbers. Updated Packaging: Updated Package Diagrams: spec 001-42168 – Changed revision from *E to *F. Added spec 51-85088 *E.
*L	6639191	07/31/2019	Updated Features: Updated 32-bit MCU Subsystem: Updated description. Added Development Ecosystem. Added PSoC Creator. Updated Functional Definition: Updated System Resources: Updated Power System: Updated description. Updated Watch Crystal Oscillator (WCO): Updated description. Updated Fixed Function Digital: Updated Serial Communication Block (SCB): Updated Special Function Peripherals: Updated LCD Segment Drive: Updated description.



Document History Page (continued)

Revision	ECN	Submission Date	Description of Change
*L (cont.)	6639191	07/31/2019	Updated Pinouts: Added Note below Table 1. Updated Electrical Specifications: Updated Analog Peripherals: Updated CSD and IDAC: Updated Table 12 (Updated details in "Details/Conditions" column corresponding to V _{REF} , V _{REF_EXT} and V _{COMPIDAC} parameters). Updated Digital Peripherals: Updated SPI: Updated Table 18 (Updated all values corresponding to TSSELSSCK parameter). Updated Ordering Information: Updated part numbers. Updated Packaging: Updated Package Diagrams: spec 001-13937 – Changed revision from *F to *G. Updated to new template. Completing Sunset Review.
*M	7026754	11/20/2020	Added Clock Sources and ModusToolbox™ in Features. Updated Development Ecosystem. Updated temperature range in Electrical Specifications: Added Q-temp MPNs for the 48-TQFP package. Updated Table 25: Updated SID.CLK#6 Description. Updated Table 39: Updated Typ. value for TJA 25-ball WLCSP. Updated Sales, Solutions, and Legal Information.
*N	7036861	12/23/2020	Updated Table 37: Updated Nomenclature to show "Extended Industrial".



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Document Number: 002-00123 Rev. *N Revised December 23, 2020 Page 42 of 42